

RD74LVC16244B

16-bit Buffers / Line Drivers with 3-state Outputs

REJ03D0527-0100

Rev.1.00

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Description

The RD74LVC16244B has sixteen line drivers with three state outputs in a 48 pin package. This device is a non inverting buffer and has two active low enables ($\overline{1G}$ to $\overline{4G}$). Each enable independently controls four buffers. Low voltage and high-speed operation is suitable at the battery drive product (note type personal computer) and low power consumption extends the life of a battery for long time operation.

Features

- $V_{CC} = 1.65 \text{ V to } 5.5 \text{ V}$
- All inputs $V_{IH} (\text{Max.}) = 5.5 \text{ V} (@V_{CC} = 0 \text{ V to } 5.5 \text{ V})$
- All outputs $V_{OUT} (\text{Max.}) = 5.5 \text{ V} (@V_{CC} = 0 \text{ V or output off state})$
- Typical V_{OL} ground bounce $< 0.8 \text{ V} (@V_{CC} = 3.3 \text{ V, } T_a = 25^\circ\text{C})$
- Typical V_{OH} undershoot $> 2.0 \text{ V} (@V_{CC} = 3.3 \text{ V, } T_a = 25^\circ\text{C})$
- High output current
 - $\pm 4 \text{ mA} (@V_{CC} = 1.65 \text{ V})$
 - $\pm 8 \text{ mA} (@V_{CC} = 2.3 \text{ V})$
 - $\pm 12 \text{ mA} (@V_{CC} = 2.7 \text{ V})$
 - $\pm 24 \text{ mA} (@V_{CC} = 3.0 \text{ V to } 5.5 \text{ V})$
- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
RD74LVC16244BTEL	TSSOP-48 pin	PTSP0048KA-A (TTP-48DBV)	T	EL (1,000 pcs/reel)

Function Table

Inputs		Output Y
\overline{G}	A	
H	X	Z
L	H	H
L	L	L

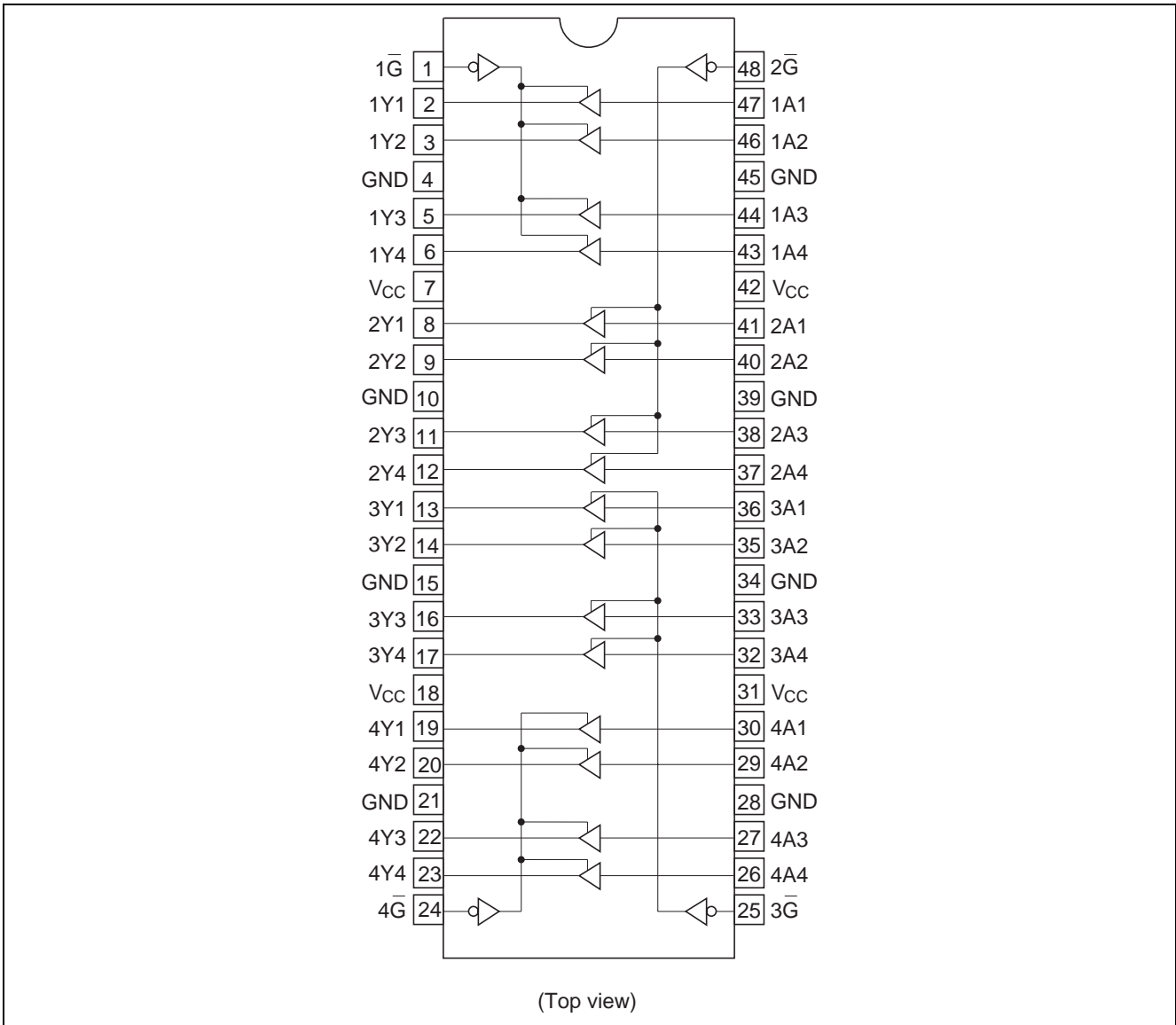
H: High level

L: Low level

X: Immaterial

Z: High impedance

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	-0.5 to 7.0	V	
Input diode current	I_{IK}	-50	mA	$V_I = -0.5$ V
Input voltage	V_I	-0.5 to 7.0	V	
Output diode current	I_{OK}	-50	mA	$V_O = -0.5$ V
		50		$V_O = V_{CC} + 0.5$ V
Output voltage	V_O	-0.5 to $V_{CC} + 0.5$	V	Output "H" or "L"
		-0.5 to 7.0		Output "Z" or $V_{CC}: OFF$
Output current	I_O	± 50	mA	
V_{CC} , GND current / pin	I_{CC} or I_{GND}	100	mA	
Storage temperature	T_{stg}	-65 to +150	$^{\circ}C$	

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	1.5 to 5.5	V	Data hold
		1.65 to 5.5		At operation
Input / Output voltage	V_I	0 to 5.5	V	\bar{G} , A
	V_O	0 to V_{CC}		Output "H" or "L"
		0 to 5.5		Output "Z" or $V_{CC}: OFF$
Operating temperature	T_a	-40 to 85	$^{\circ}C$	
Output current	I_{OH}	-4	mA	$V_{CC} = 1.65$ V
		-8		$V_{CC} = 2.3$ V
		-12		$V_{CC} = 2.7$ V
		-24		$V_{CC} = 3.0$ V to 5.5 V
	I_{OL}	4	mA	$V_{CC} = 1.65$ V
		8		$V_{CC} = 2.3$ V
		12		$V_{CC} = 2.7$ V
		24		$V_{CC} = 3.0$ V to 5.5 V
Input rise / fall time ^{*1}	t_r, t_f	20	ns/V	$V_{CC} = 1.65$ V to 2.7 V
		10		$V_{CC} = 3.0$ V to 5.5 V

Notes: 1. This item guarantees maximum limit when one input switches.

Waveform: Refer to test circuit of switching characteristics.

Electrical Characteristics

Item	Symbol	V _{CC} (V)	Ta = -40 to 85°C		Unit	Test Conditions
			Min	Max		
Input voltage	V _{IH}	1.65 to 1.95	V _{CC} ×0.65	—	V	
		2.3 to 2.7	1.7	—		
		2.7 to 3.6	2.0	—		
		4.5 to 5.5	V _{CC} ×0.7	—		
	V _{IL}	1.65 to 1.95	—	V _{CC} ×0.35	V	
		2.3 to 2.7	—	0.7		
		2.7 to 3.6	—	0.8		
		4.5 to 5.5	—	V _{CC} ×0.3		
Output voltage	V _{OH}	1.65 to 5.5	V _{CC} -0.2	—	V	I _{OH} = -100 μA
		1.65	1.2	—		I _{OH} = -4 mA
		2.3	1.7	—		I _{OH} = -8 mA
		2.7	2.2	—		I _{OH} = -12 mA
		3.0	2.4	—		
		3.0	2.2	—		I _{OH} = -24 mA
		4.5	3.8	—		
	V _{OL}	1.65 to 5.5	—	0.2	V	I _{OL} = 100 μA
		1.65	—	0.45		I _{OL} = 4 mA
		2.3	—	0.7		I _{OL} = 8 mA
		2.7	—	0.4		I _{OL} = 12 mA
		3.0	—	0.55		
		3.0	—	0.55		I _{OL} = 24 mA
		4.5	—	0.55		
Input current	I _{IN}	0 to 5.5	—	±5.0	μA	V _{IN} = 5.5 V or GND
Output leak current	I _{OFF}	0	—	±5.0	μA	V _{IN} / V _{OUT} = 5.5 V
Off state output current	I _{OZ}	2.7 to 5.5	—	±5.0	μA	V _{IN} = V _{CC} or GND V _O = 5.5 V or GND
Quiescent supply current	I _{CC}	2.7 to 3.6	—	±10	μA	V _{IN} = 3.6 V to 5.5 V
		2.7 to 5.5	—	10		V _{IN} = V _{CC} or GND
	ΔI _{CC}	2.7 to 3.6	—	500	μA	V _{IN} = one input at (V _{CC} -0.6)V, other inputs at V _{CC} or GND

Switching Characteristics

Item	Symbol	V _{CC} (V)	Ta = -40 to 85°C			Unit	From (Input)	To (Output)
			Min	Typ	Max			
Propagation delay time	t _{PLH}	1.8±0.15	1.0	—	10.9	ns	A	Y
	t _{PHL}	2.5±0.2	1.0	—	7.9			
		2.7	1.0	—	5.8			
		3.3±0.3	1.5	—	5.2			
		5.0±0.5	1.0	—	4.0			
Output enable time	t _{ZH}	1.8±0.15	1.0	—	12.6	ns	\bar{G}	Y
	t _{ZL}	2.5±0.2	1.0	—	9.6			
		2.7	1.0	—	8.2			
		3.3±0.3	1.5	—	7.5			
		5.0±0.5	1.0	—	5.5			
Output disable time	t _{HZ}	1.8±0.15	1.0	—	12.1	ns	\bar{G}	Y
	t _{LZ}	2.5±0.2	1.0	—	7.8			
		2.7	1.0	—	7.7			
		3.3±0.3	1.5	—	7.0			
		5.0±0.5	1.0	—	6.0			
Between output pins skew*1	t _{OSLH}	1.8±0.15	—	—	—	ns		
	t _{OSHL}	2.5±0.2	—	—	—			
		2.7	—	—	—			
		3.3±0.3	—	—	1.0			
		5.0±0.5	—	—	1.0			
Input capacitance	C _{IN}	3.3	—	4.0	—	pF		
Output capacitance	C _O	3.3	—	8.0	—	pF		

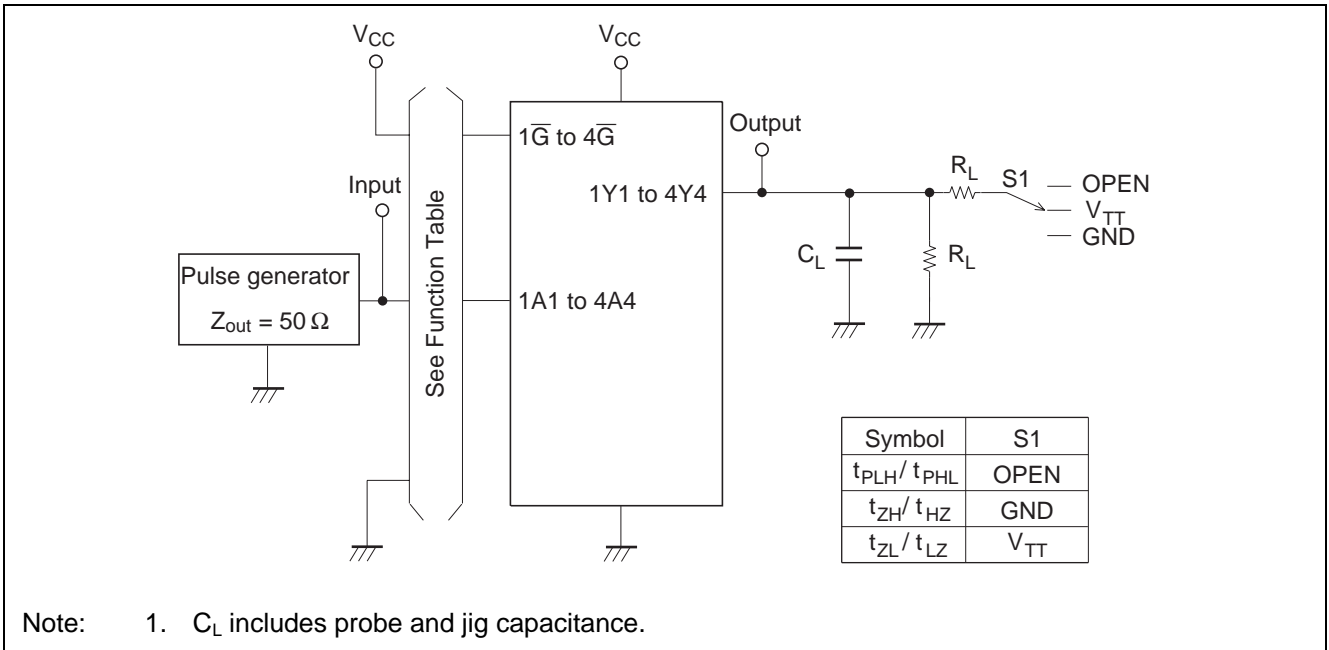
Note: 1. This parameter is characterized but not tested.

$$t_{OSLH} = |t_{PLHm} - t_{PLHn}|, t_{OSHL} = |t_{PHLm} - t_{PHLn}|$$

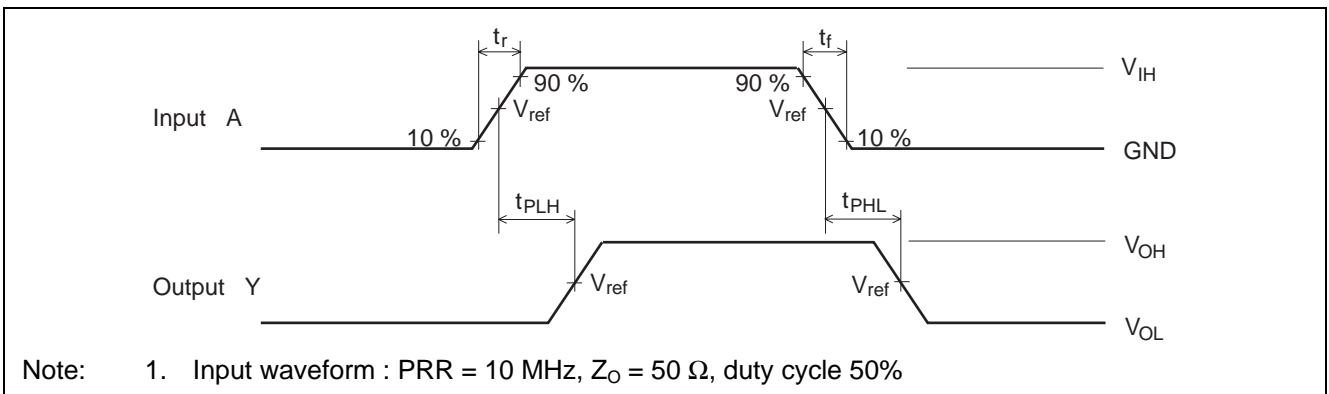
Operating Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C			Unit	Test conditions
			Min	Typ	Max		
Power dissipation Capacitance	C _{PD}	1.8	—	25.0	—	pF	f = 10 MHz
		2.5	—	25.0	—		
		3.3	—	27.0	—		
		5.0	—	32.0	—		

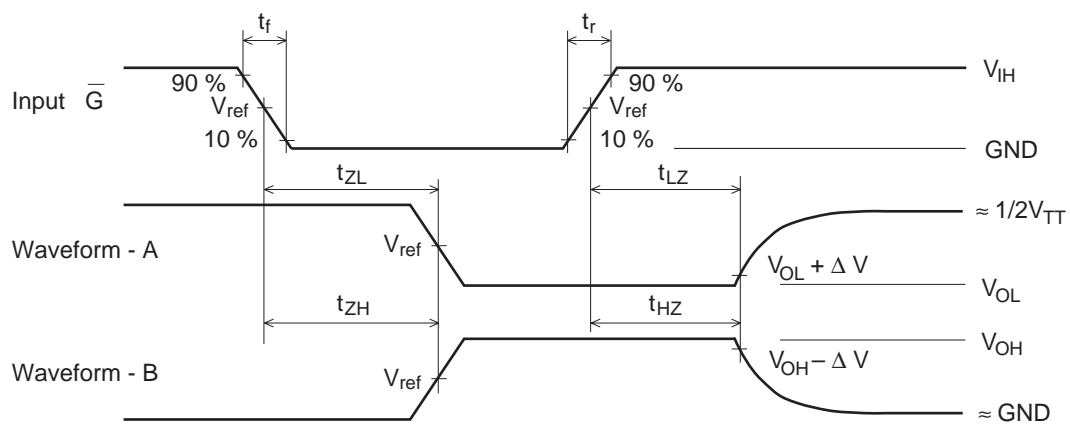
Test Circuit



Waveforms – 1



Waveforms – 2

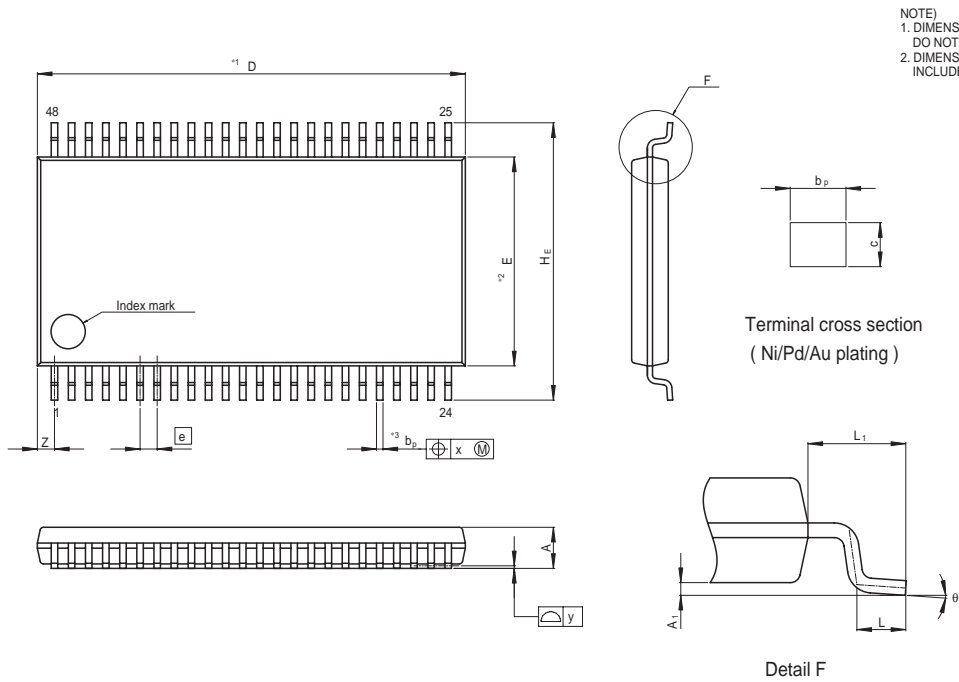


V_{CC} (V)	INPUTS		V_{ref}	V_{TT}	C_L	R_L	ΔV
	V_I	t_r/t_f					
$V_{CC} = 1.8 \pm 0.15$ V	V_{CC}	≤ 2 ns	$1/2 V_{CC}$	$2 \times V_{CC}$	30 pF	1.0 k Ω	0.15 V
$V_{CC} = 2.5 \pm 0.2$ V	V_{CC}	≤ 2 ns	$1/2 V_{CC}$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
$V_{CC} = 2.7$ V	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
$V_{CC} = 3.3 \pm 0.3$ V	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
$V_{CC} = 5.0 \pm 0.5$ V	V_{CC}	≤ 2.5 ns	$1/2 V_{CC}$	$2 \times V_{CC}$	50 pF	500 Ω	0.3 V

- Notes:
1. Input waveform : PRR = 10 MHz, $Z_O = 50 \Omega$, duty cycle 50%
 2. Waveform – A shows input conditions such that the output is "L" level when enable by the output control.
 3. Waveform – B shows input conditions such that the output is "H" level when enable by the output control.

Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TSSOP48-6.1x12.5-0.50	PTSP0048KA-A	TTP-48DBV	0.2g



NOTE)
 1. DIMENSIONS*1 (Nom)*AND*2*
 DO NOT INCLUDE MOLD FLASH
 2. DIMENSION*3*DOES NOT
 INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	12.5	12.7
E	—	6.10	—
A ₂	—	—	—
A ₁	0.08	0.13	0.18
A	—	—	1.20
b _p	0.14	0.19	0.24
b ₁	—	—	—
c	0.10	0.15	0.20
c ₁	—	—	—
θ	0°	—	8°
H _E	7.90	8.10	8.30
e	—	0.50	—
x	—	—	0.08
y	—	—	0.10
Z	—	—	0.65
L	0.4	0.5	0.6
L ₁	—	1.0	—

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